

Customer No.: 31561
Application No.: 10/711,863
Docket No.: 14098-US-PA

REMARKS

Claims 11 and 13 have been amended to include subject matter fabricated by the method of claim 1, while claim 14 is currently canceled hereby.

Claim Rejections – 35 U.S.C. § 102

The Office Action rejected claims 11, 13-15 under 35 U.S.C. 102(b) as being anticipated by US 3,354,543 (Lawrence).

In response thereto, Applicants submit that such a method as set forth in allowable claim 1 is neither taught, disclosed, nor suggested by Lawrence, or any of the other cited references, taken alone or in combination.

Similarly, applicant submits that such a circuit board fabricated by the method of allowable claim 1 or claim 3 is neither taught, disclosed, nor suggested by Lawrence, or any of the other cited references, taken alone or in combination, and thus should be allowed.

Lawrence teaches an electroplating process configuring a conductive copper layer over a surface of the through hole (Column 6, lines 1-15; FIG. 2(e)). However, Lawrence fails to teach the structure and process of “**a conductive column formed by a conductive material filling with the through hole from a position where the blind ends of the first and second blind holes connect with each other and extend toward two ends of the through hole**” (Emphasis

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added)" as set forth in claims 11 and 13. Therefore, claims 11 and 13 and the dependent claim 15 are submitted to be patentable over Lawrence, or any of the other cited references, taken alone or in combination, and thus should be allowed.

Claims 11 and 13 are rejected under 35 U.S.C. 102(b) as being anticipated by US 6,114,240 (Akram).

In response thereto, Applicant has amended claim 11 and 13 to include subject matter fabricated by the method of claim 1, and hereby otherwise traverses this rejection.

Applicants submit that such a method as set forth in allowable claim 1 is neither taught, disclosed, nor suggested by Akram or any of the other cited references, taken alone or in combination.

Similarly, applicant submits that such a circuit board fabricated by the method of allowable claim 1 or claim 3 is neither taught, disclosed, nor suggested by Akram, or any of the other cited references, taken alone or in combination, and thus should be allowed.

Akram teaches a process steps for fabricating the conductive vias in FIG. 2A-2D. However, Lawrence fails to teach the structure and process of "**a conductive column formed by a conductive material filling with the through hole from a position where the blind ends of the first and second blind holes connect with each other and extends towards two ends of the through hole** (Emphasis added)" as set forth in claims 11 and 13. Therefore, claims 11 and

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13 and the dependent claim 15 are submitted to be patentable over Akarm, or any of the other cited references, taken alone or in combination, and thus should be allowed.

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CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 11, 13, 15, 17 and 18 are in proper condition for allowance and an action to such effect is earnestly solicited. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date :

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